



# Multi-Domain Processors Design Overview

Stefan Rusu

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# Big picture

- Part I discusses the main issues in multi-domain processor design and presents many concrete examples proposed to date
- Part II considers the NoC communication and router design, as well as QoS issues in MPSoCs
- Part III considers design partitioning into multi-VFIs and control policies for multi-domain processors
- Part IV discusses DVFS issues in presence of process variations and theoretical bounds of achievable power savings
- Low-power multi-processor design and power management techniques depend critically on integrating various platform and application characteristics

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3

## ISCA-2010 Tutorial #2

# Multi-Domain Processors Design Overview

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4

# Why Multi-Domain Processors?

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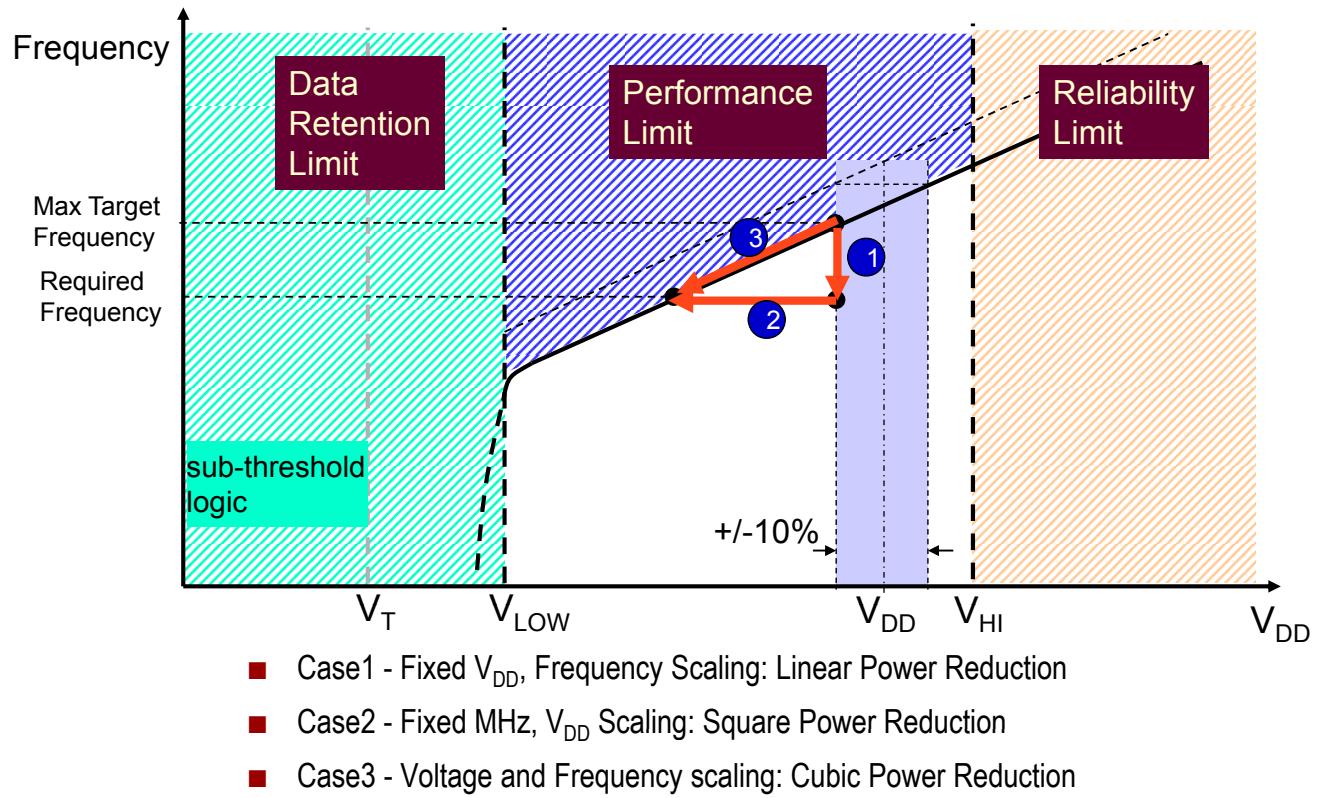
- Adapt supply voltage and clock frequency to the underlying circuit needs
  - ▼ Special supply voltage for large cache SRAM arrays
  - ▼ Adapt clock frequency to standard interface needs (e.g. DDR800)
- Reduce operating voltage and frequency to save power in idle or lower performance blocks
  - ▼ Power and clock gating in idle circuit islands
  - ▼ Run last level cache at half frequency
- Clock and voltage knobs are usually used together to enable a cubed power reduction factor
  - ▼ A 10% reduction in both voltage and frequency provides a 30% reduction in power consumption

# Multi-Domain Processors Design Overview

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- Voltage / frequency scaling basics
- Multi-domain server processors
  - ▼ Power gating
  - ▼ Core and cache recovery
  - ▼ Split vs. connected supplies
  - ▼ Globally Asynchronous, Locally Synchronous (GALS)
- Cell phone processors
- Media processors
- Dual voltage supply at the cell level
- Future directions
- Summary

# Voltage and Frequency Scaling



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[J. Rosal, ISSCC 2006]

7

# Core Power Management States

	C0 HFM	C0 LFM	C1/C2	C4	C6
Core voltage					
Core clock			OFF	OFF	OFF
PLL				OFF	OFF
L1 caches					
L2 caches					
Wakeup time	active	active			
Power					

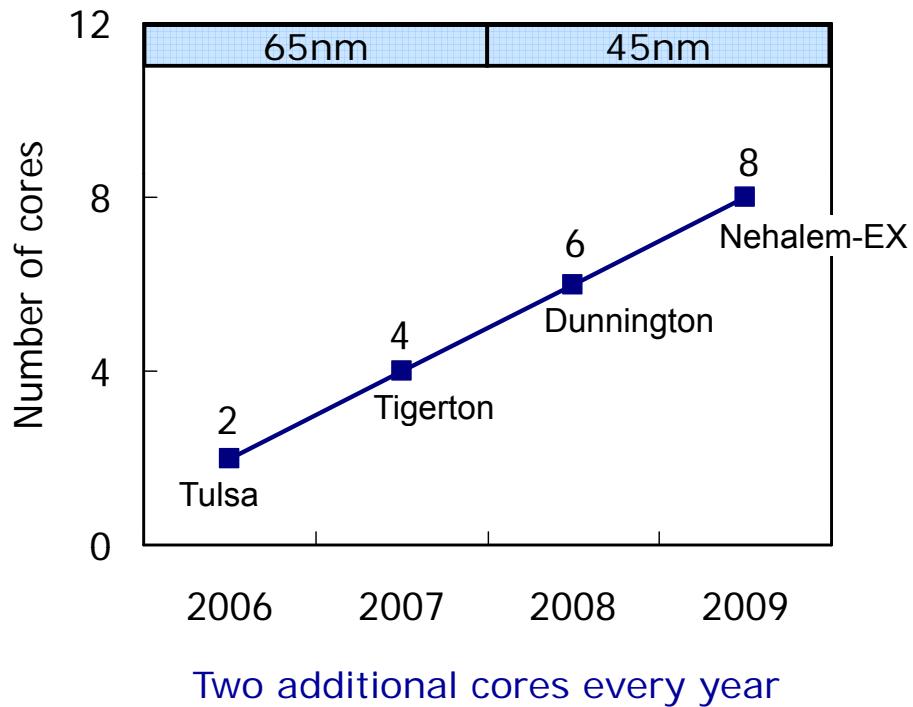
Modulating the processor core voltage and frequency  
enables lower power states

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[Gerosa, A-SSCC 2008]

8

# Xeon® EX Multi-Core Scaling Trend

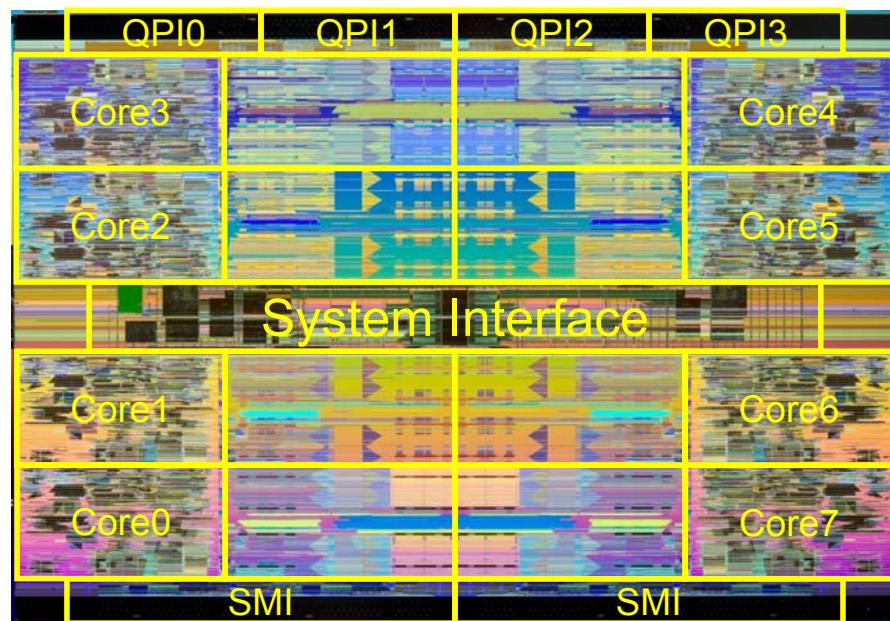


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[Rusu, ISSCC 2009]

9

## 8-Core Xeon® Processor



The largest device count reported for a microprocessor

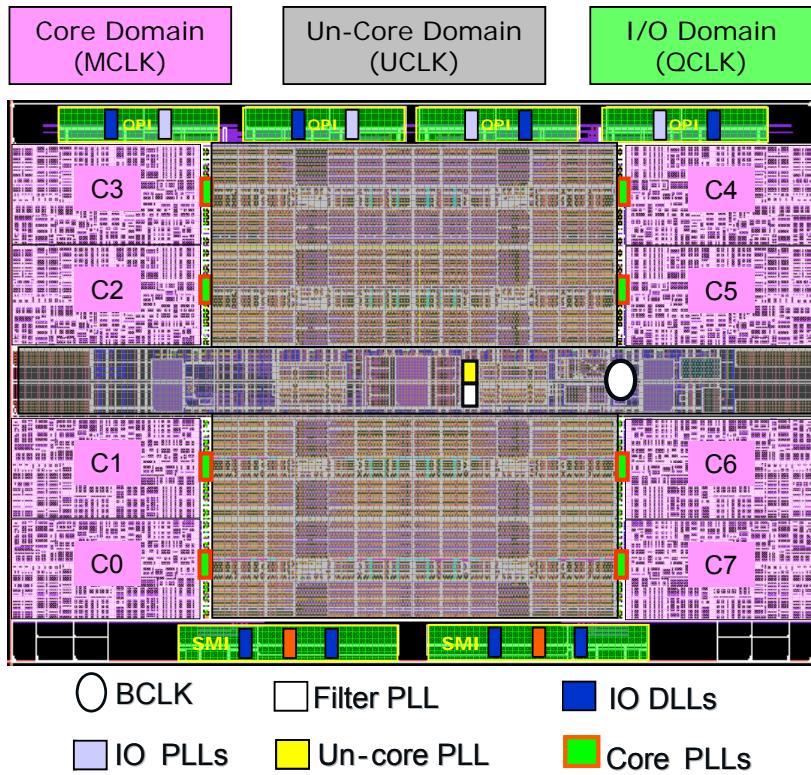
2.3B transistors

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[Rusu, ISSCC 2009]

10

# 8-Core Xeon® Processor Clock Domains

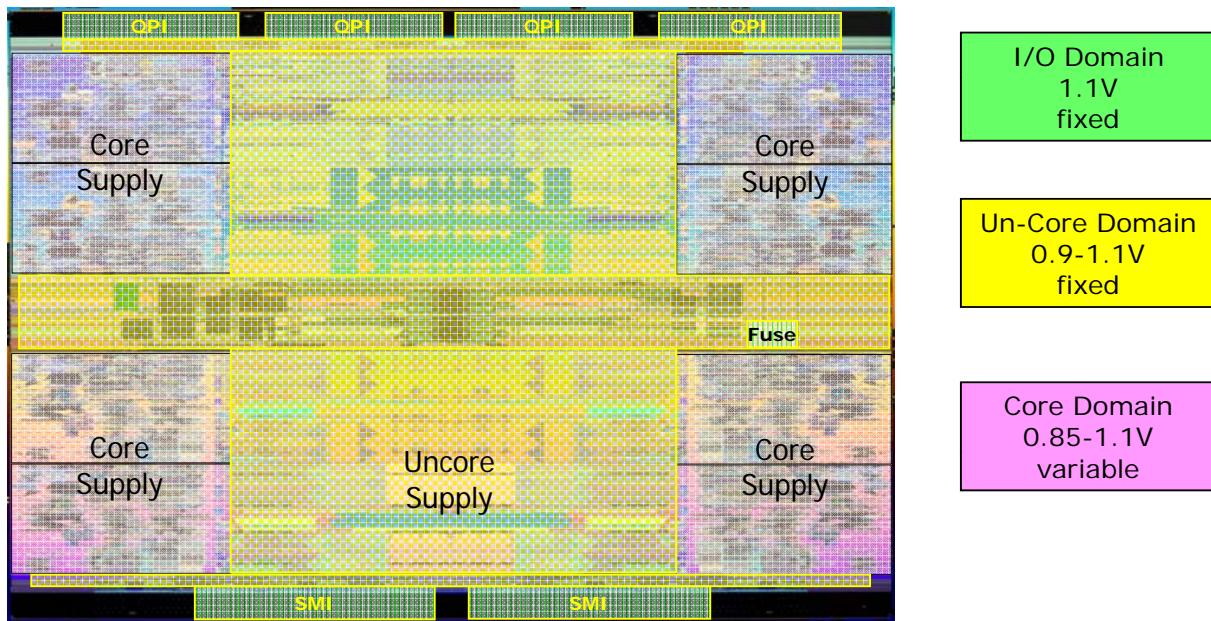


- 3 primary clock domains:
  - ▼ Core
  - ▼ Un-core
  - ▼ I/O
- 16 PLLs & 8 DLLs
  - ▼ Single system clock input (BCLK)

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[Rusu, ISSCC 2009] 11

# 8-Core Xeon® Processor Voltage Domains

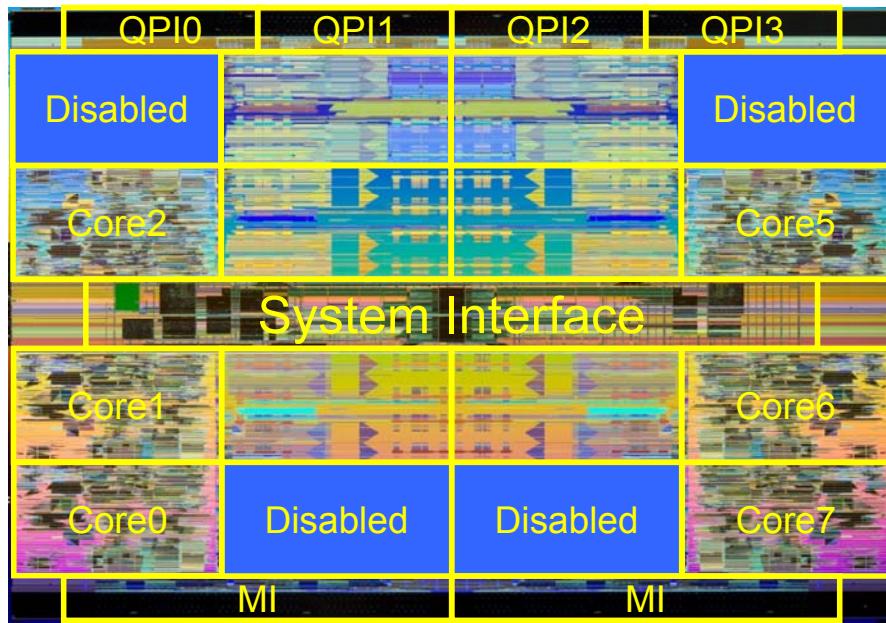


Multiple voltage domains minimize power consumption across the core and uncore areas

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[Rusu, A-SSCC 2009] 12

# Core and Cache Recovery Example



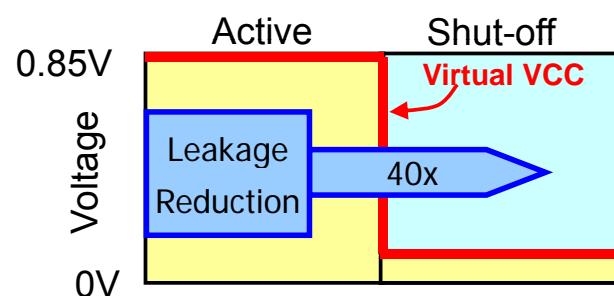
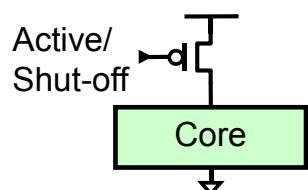
Disabled 2 cores and 2 cache slices

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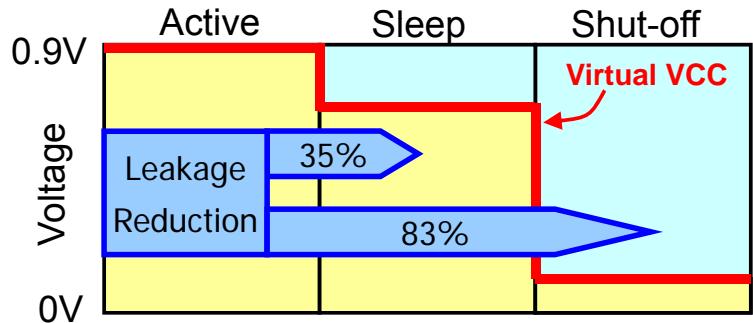
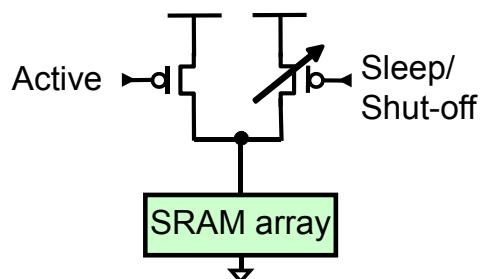
[Rusu, ISSCC 2009] 13

## Minimize Power in Disabled Blocks

- Disabled cores ► Power gated

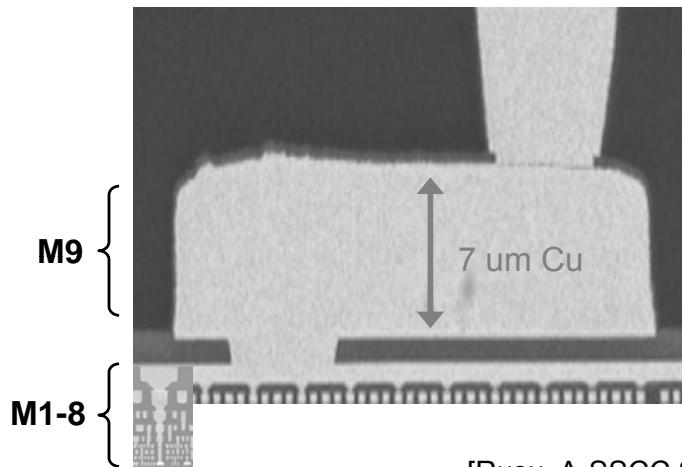
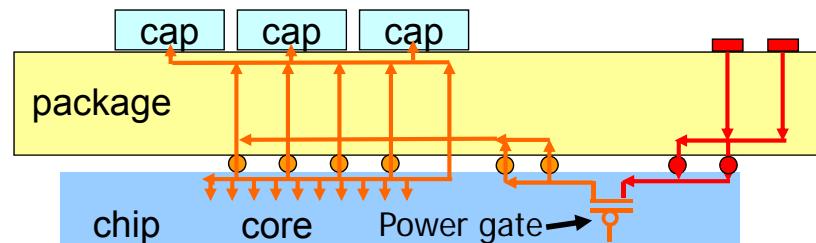


- Disabled cache slices ► All major arrays in shut-off



# Core Power Gating

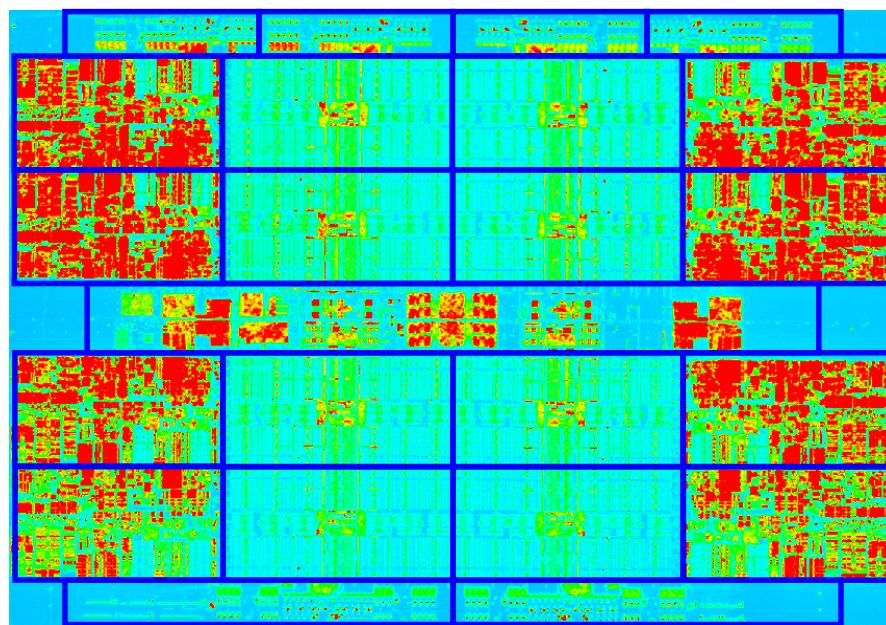
- Resistance target: less than 1% performance loss
- New package-like metal layer on silicon was developed
- M9 has ~10X lower resistance than M8



[Rusu, A-SSCC 2009] 15

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## Core and Cache Recovery – Infrared Image

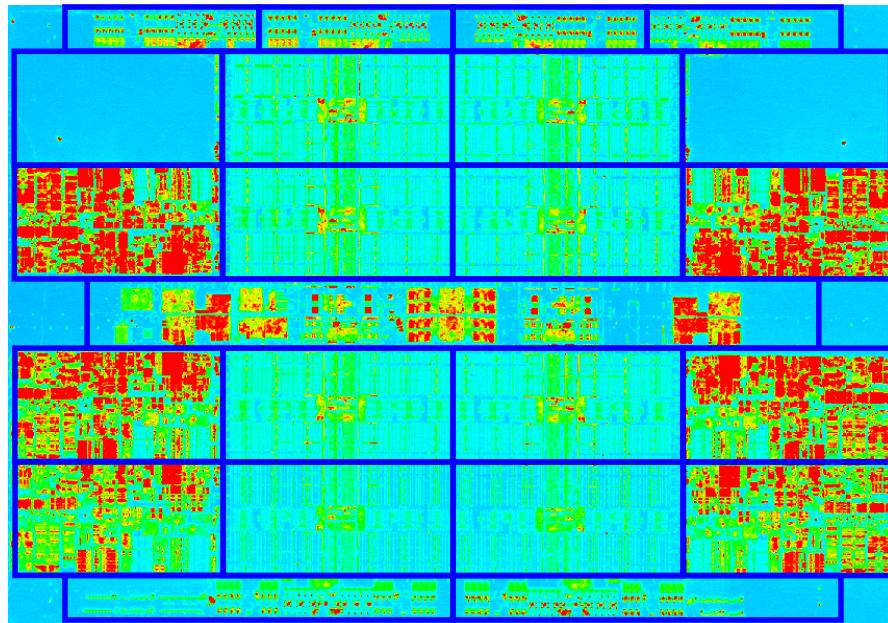


All cores and cache slices are enabled

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[Rusu, ISSCC 2009] 16

# Core and Cache Recovery – Infrared Image



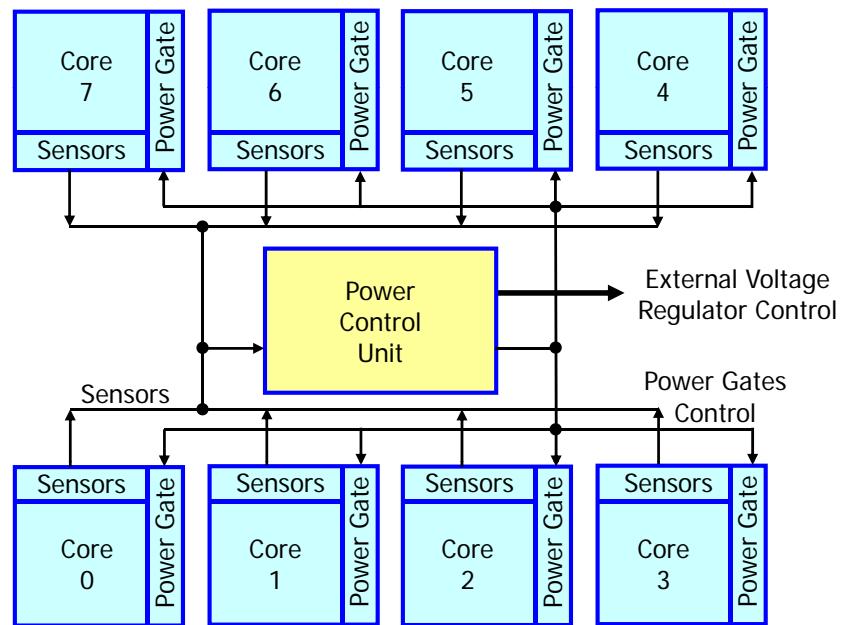
Shut-off 2 cores (top row) and 2 cache slices (bottom row)

Disabled blocks are clock and power gated

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[Rusu, ISSCC 2009] 17

## Power Management Unit

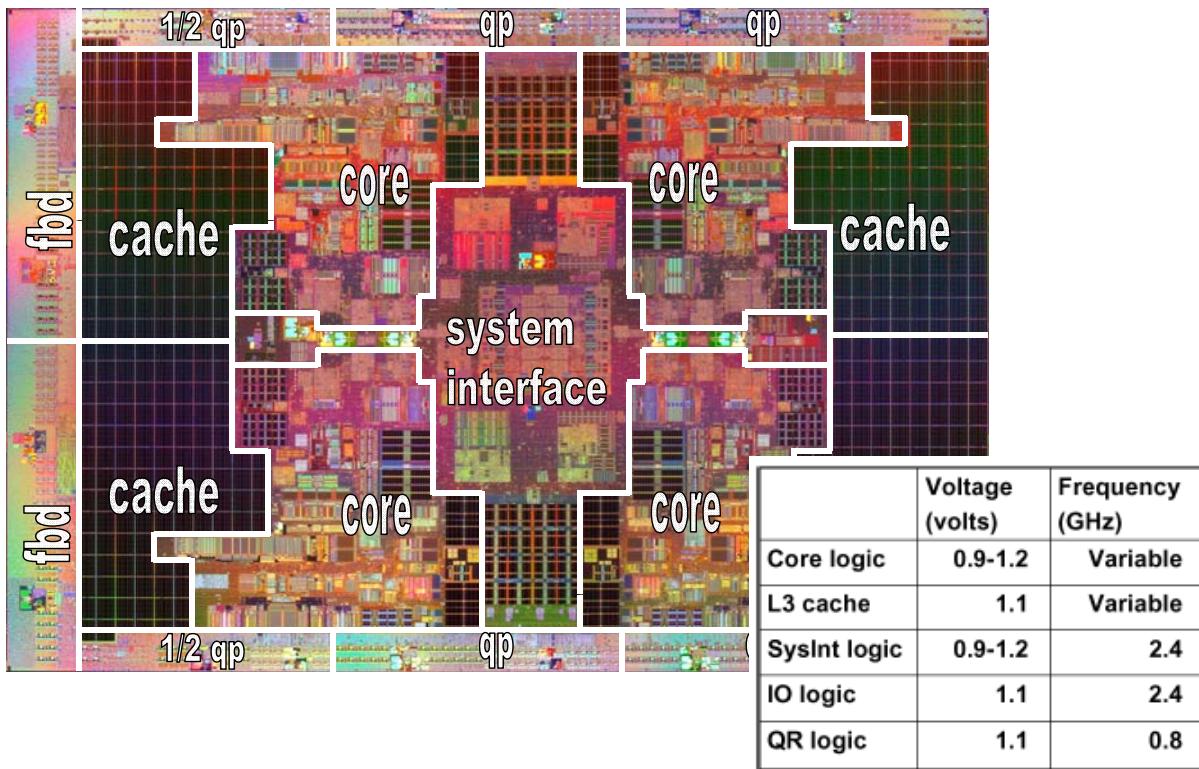


PMU controls processor voltage and frequency based  
on compute loading and thermal data

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[Rusu, A-SSCC 2009] 18

## 65nm Itanium® Processor Domains

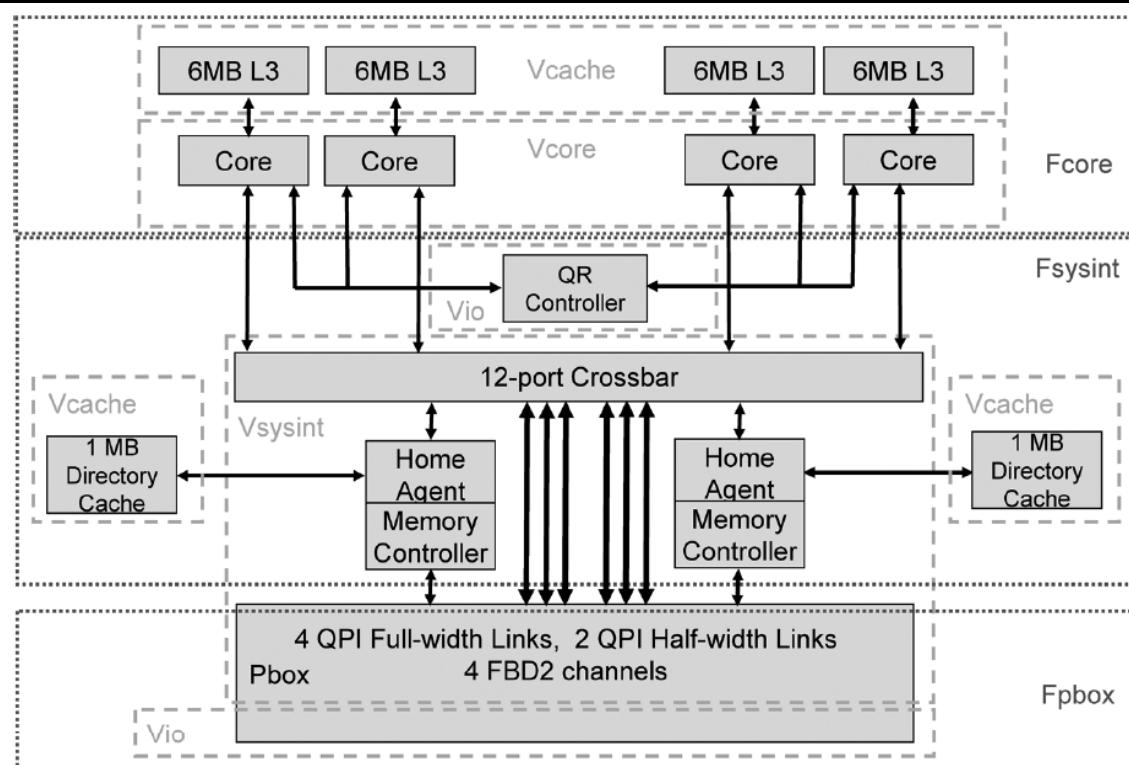


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[Stackhouse, JSSC 2009]

19

## 65nm Itanium® Processor Domains

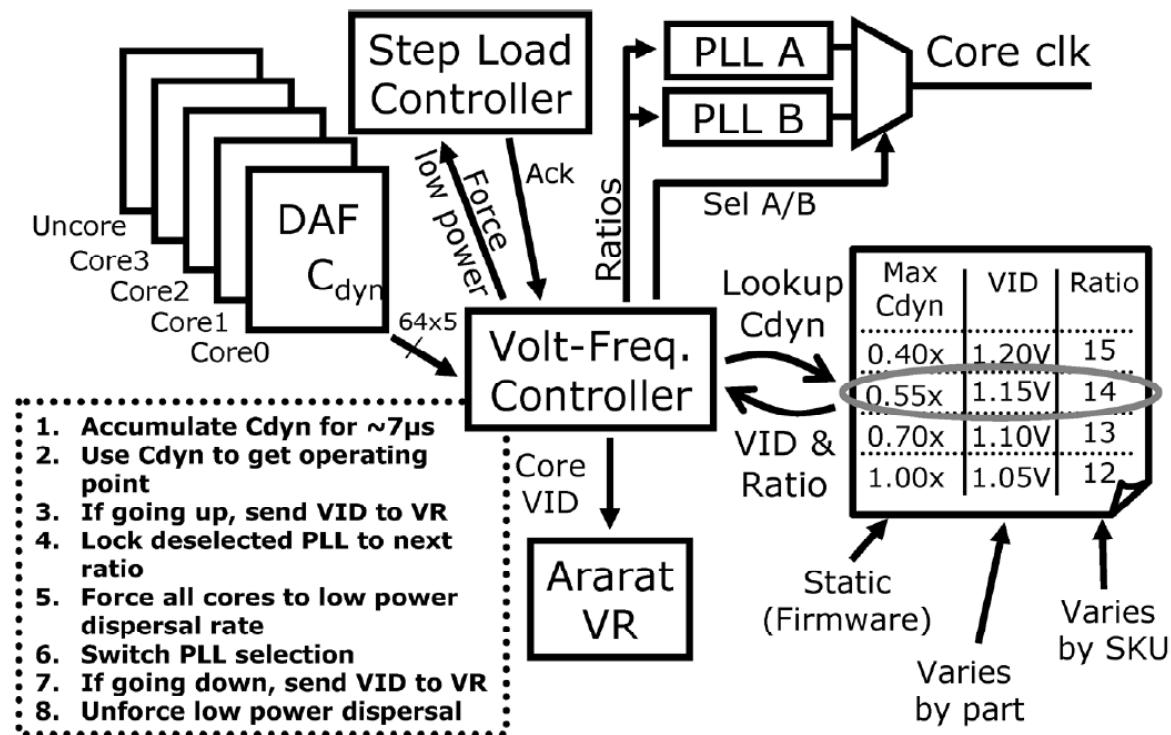


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[Stackhouse, JSSC 2009]

20

# Adaptive Voltage and Frequency Control



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[Stackhouse, JSSC 2009]

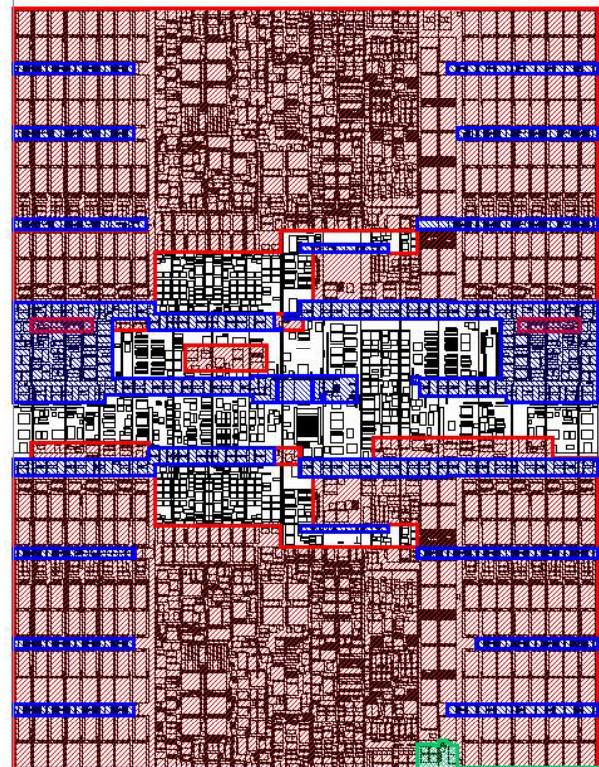
21

# IBM POWER6 Multi-Rail Design

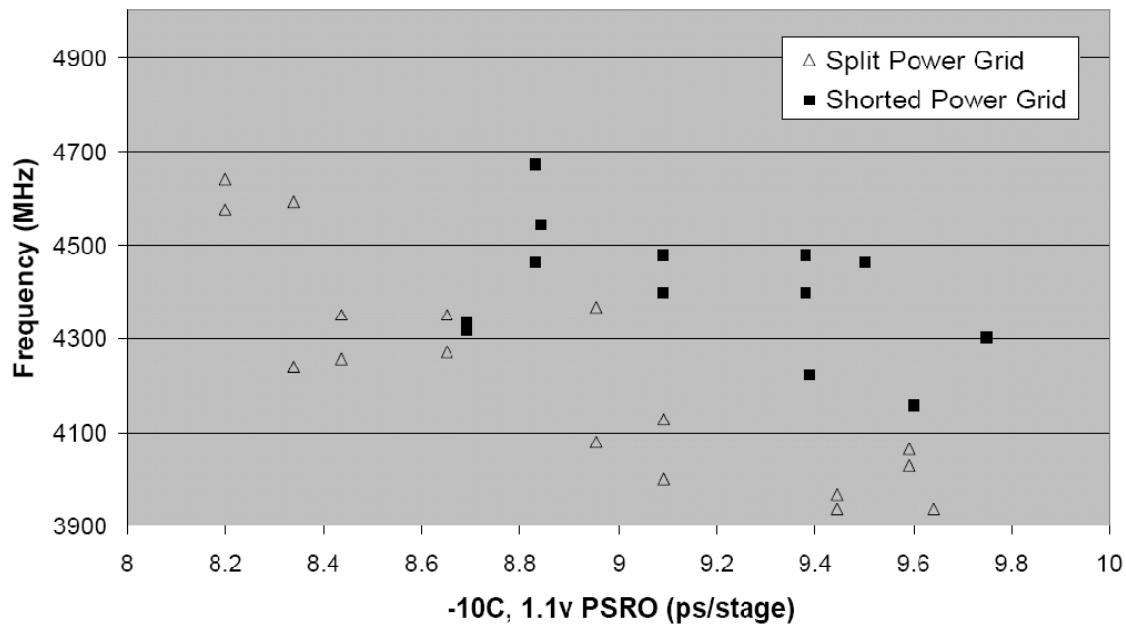
- POWER6 infrastructure contains 4 voltage domains

Rail	Purpose	Plot Color
VDD	Logic	All
VCS	Array	Red
VIO	IO, PLL, MC	Blue
VSB	Power-up	Green

- Multi-rail power grid defined based on macro current requirements and iterative IR analysis of each rail.
  - Voltage domain of macros and global signals explicitly specified in RTL and validated by checking tools.



# Split vs. Connected Core Supplies

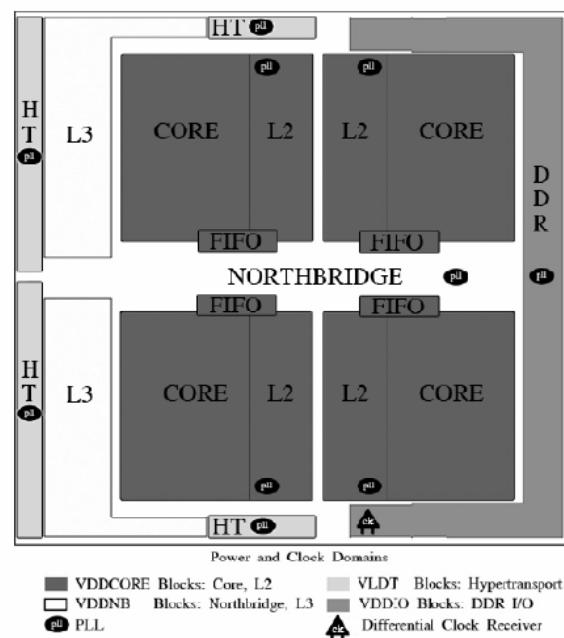


Performance sort ring oscillators (PSRO) show that the connected power chips exhibit a 3-5% fmax improvement

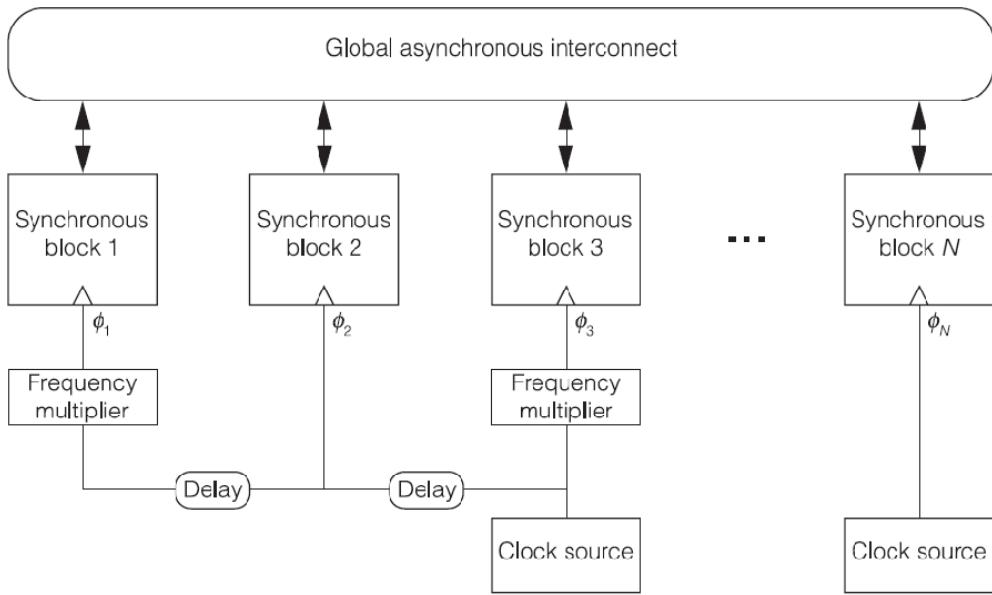
## AMD Barcelona Processor Voltage Domains

Multiple supplies for power optimization and isolation

- VDDCORE: 0.8V-1.4V
  - Core and L2: 2.0GHz and up
- VDDNB: 0.8V-1.4V
  - Northbridge and L3: 75% of core
- VLDT: 1.2V
  - HyperTransport links
- VDDIO: 1.8V (VTT:0.9V)
  - DDR I/O
- VDDA: 2.5V
  - PLLs (10 across the die) + Thermal



# Globally Asynchronous, Locally Synchronous (GALS)



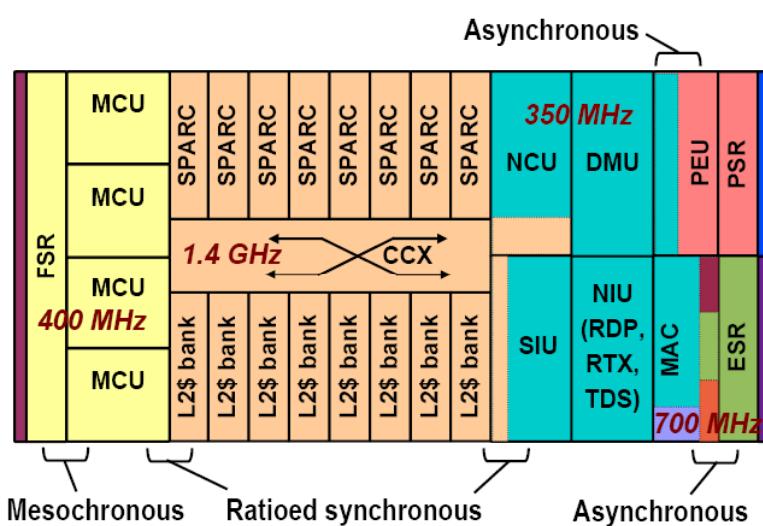
GALS methodology is a natural approach for SoC design, allowing the integration of independently designed blocks operating at different frequencies

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[P. Teehan, IEEE D&T of C 2007]

25

## Sun/Oracle Niagara2 Clocking

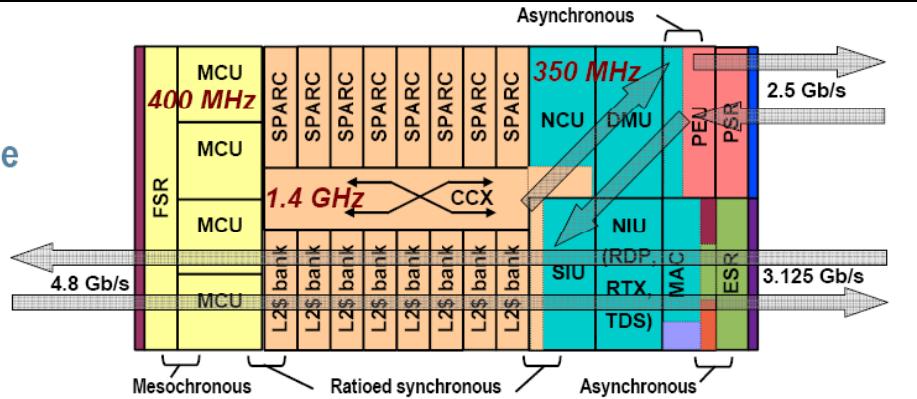


REF	133/167/200 MHz
CMP	1.4 GHz
IO	350 MHz
IO2X	700 MHz
FSR.refclk	133/167/200 MHz
FSR.bitclk	1.6/2.0/2.4 GHz
FSR.byteclk	267/333/400 MHz
DR	267/333/400 MHz
PSR.refclk	100/125/250 MHz
PSR.bitclk	1.25 GHz
PSR.byteclk	250 MHz
PCI-Ex	250 MHz
ESR.refclk	156 MHz
ESR.bitclk	1.56 GHz
ESR.byteclk	312.5 MHz
MAC.1	312.5 MHz
MAC.2	156 MHz

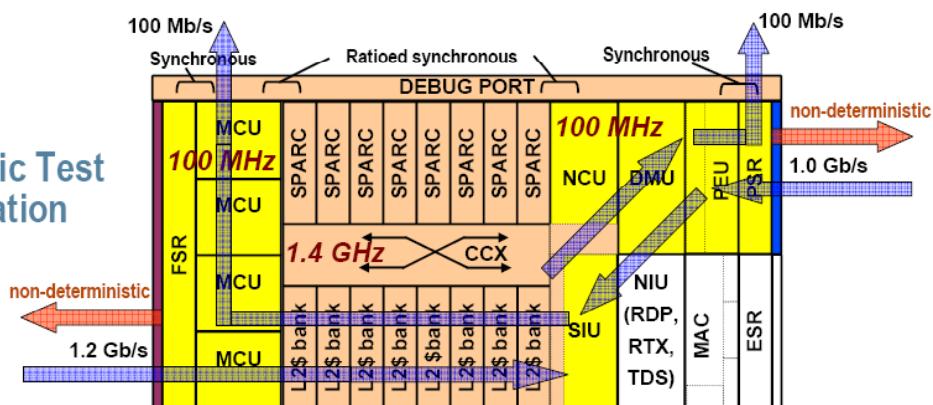
SoC processors must handle multiple clock domains for the various external interfaces

# Deterministic Test Mode

Mission Mode Operation



Deterministic Test Mode Operation



RC

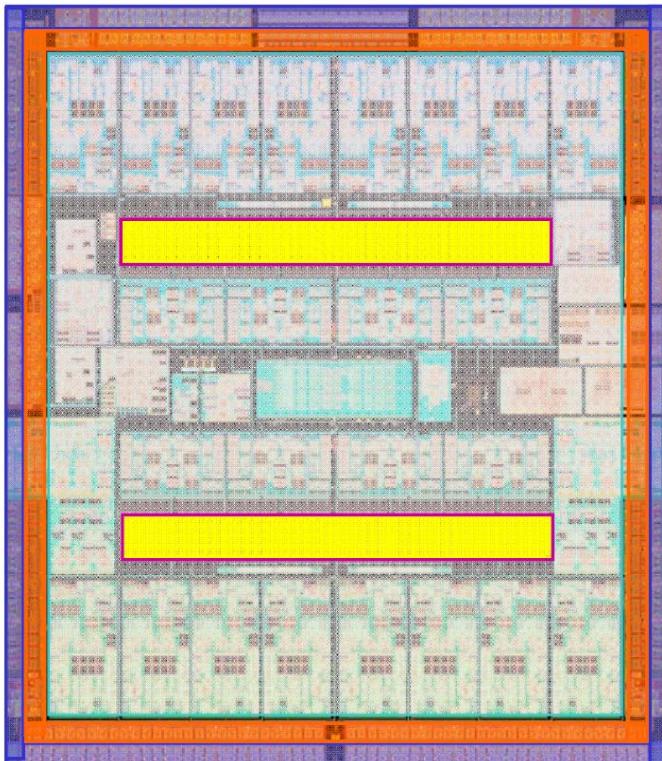
27

# Sun/Oracle Rainbow Falls SoC Processor



- TSMC 40nm process, 11 ML
- 16 8-threaded SPARC<sup>®</sup> cores
- 16KB 8-way Icache
- 64-entry ITLB
- 8KB 4-way Dcache
- 128-entry DTLB
- Enhanced multiply/add FGU and crypto per core
- Unified 6MB 16-bank 24-way L2 cache
- Hierarchical crossbar
- 4 DDR3 channels at 6.4Gbps
- 6 coherency links at 9.6Gbps
- 2x8 PCIe 2.0 at 5GTS
- 2x10G XAUI Ethernet

# Sun/Oracle Rainbow Falls Voltage Domains



Vdd_core (VDDC) 0.8V ~ 1.1V	All Logic
Vdd_memory 0.9V ~ 1.1V	L2D Memory Cells
Vdd_analog 1.0V	PLL/SerDes
VDDT/VDDR 1.5V	I/O
VNW (VDDC +/- 0.3V)	PMOS Bias
VNWM	L2D Memory Cells PMOS Bias
VSB (VSS +/- 0.3V)	NMOS Bias

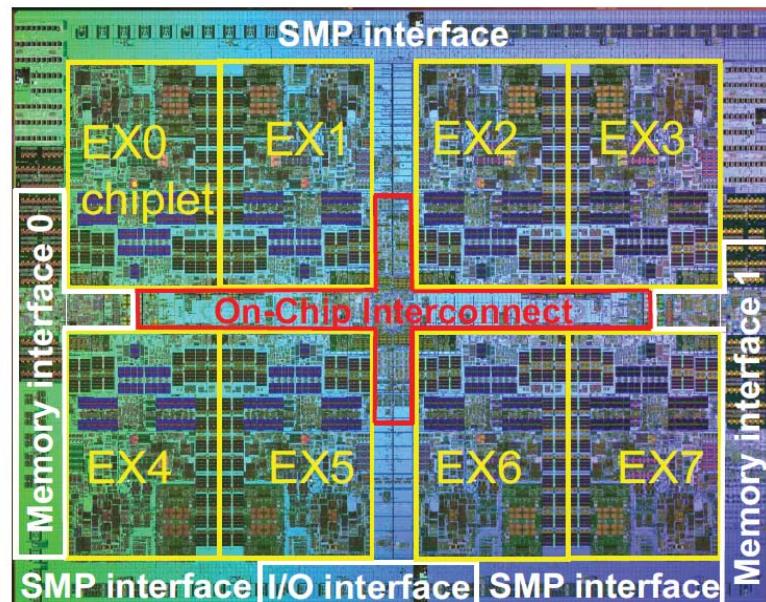
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[Shin, ISSCC 2010]

29

## IBM POWER7™ Processor

- 3.0 to 4.14 GHz
- 45nm CMOS SOI
- 567mm<sup>2</sup>
- 1.2B transistors
- Eight processor cores
  - 12 execution units per core
  - 4 Way SMT per core
  - 32 Threads per chip
  - 256KB L2 per core



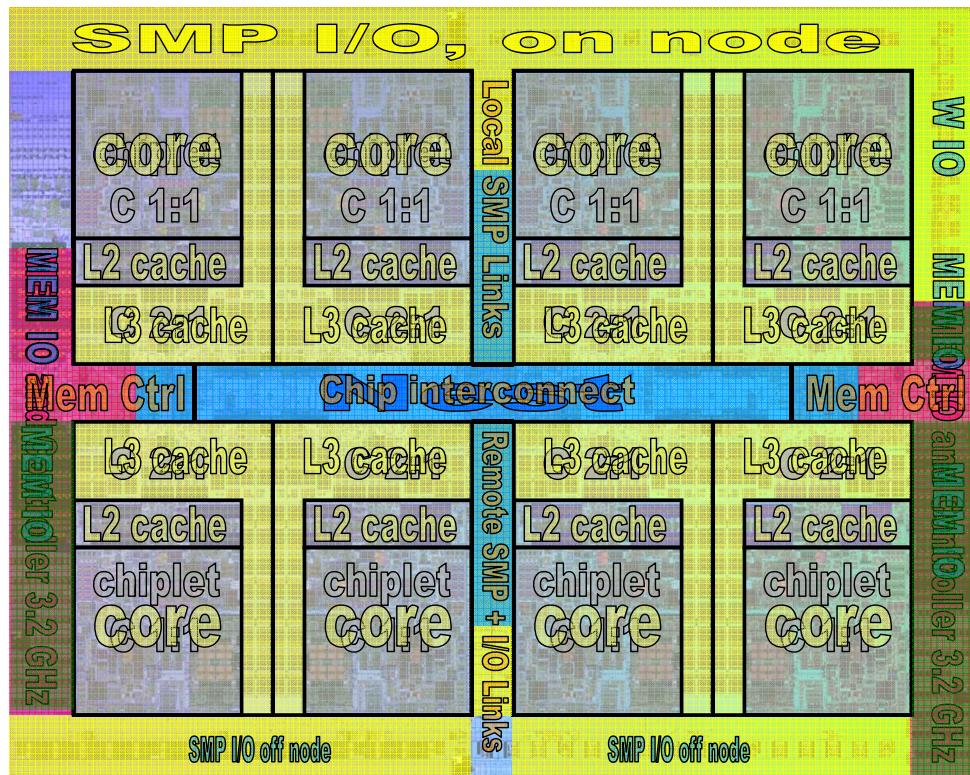
- 32MB on chip eDRAM shared L3
- Dual DDR3 Memory Controllers
  - 100GB/s Memory bandwidth per chip sustained

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[Wendel, ISSCC 2010]

30

## P7 Clock Domains

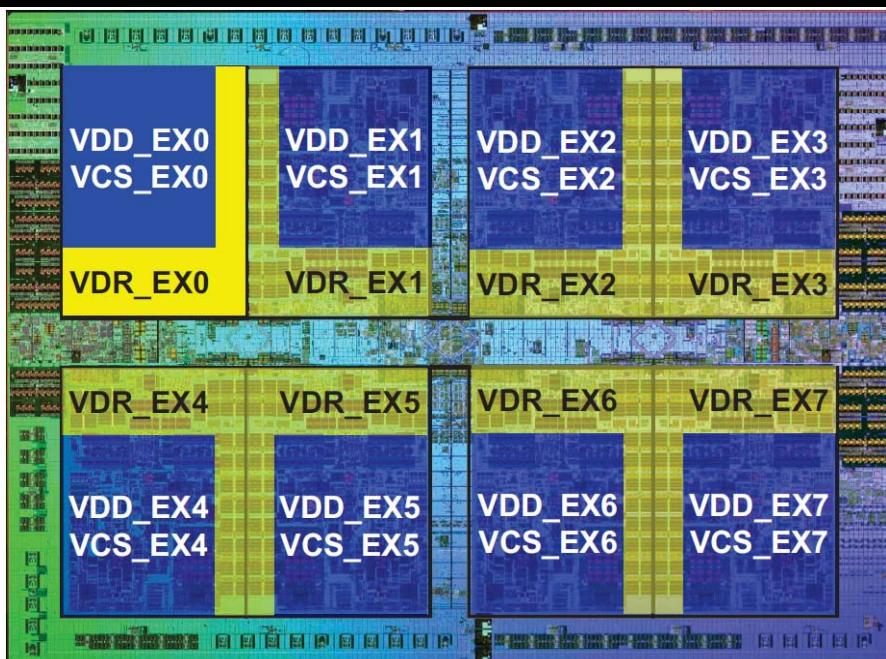


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[Wendel, ISSCC 2010]

31

## P7 Voltage Domains (1)

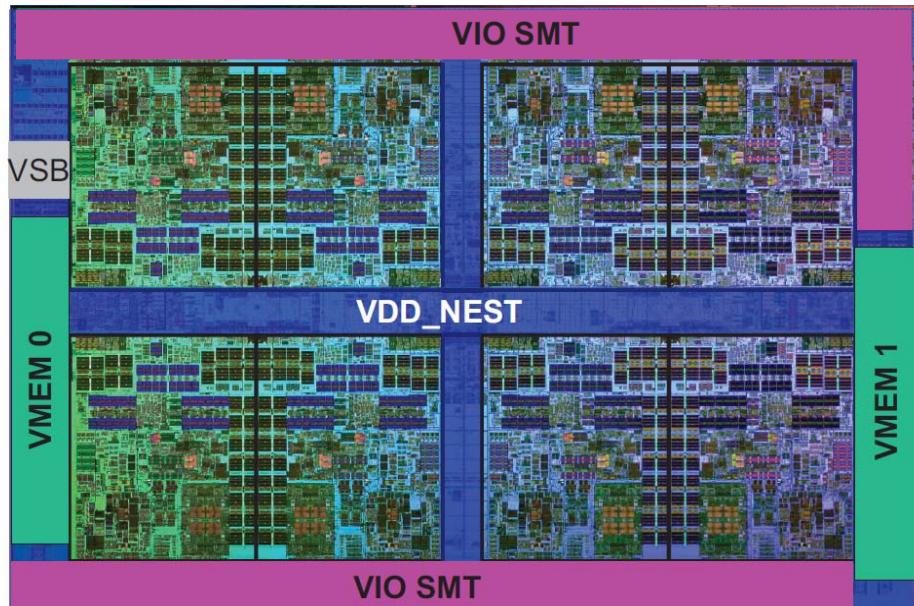


Name: # = 0 to 7	Meaning	Type of Voltage	Min.	Max.
VDD_EX#	Logic supply for Chiplet #	Adaptive, Dynamic	0.7V	1.3V
VCS_EX#, VDR_EX#	Array supply for chiplet#, DRAM supply for chiplet #	Adaptive, Dynamic	0.8V	1.3V

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32

## P7 Voltage Domains (2)

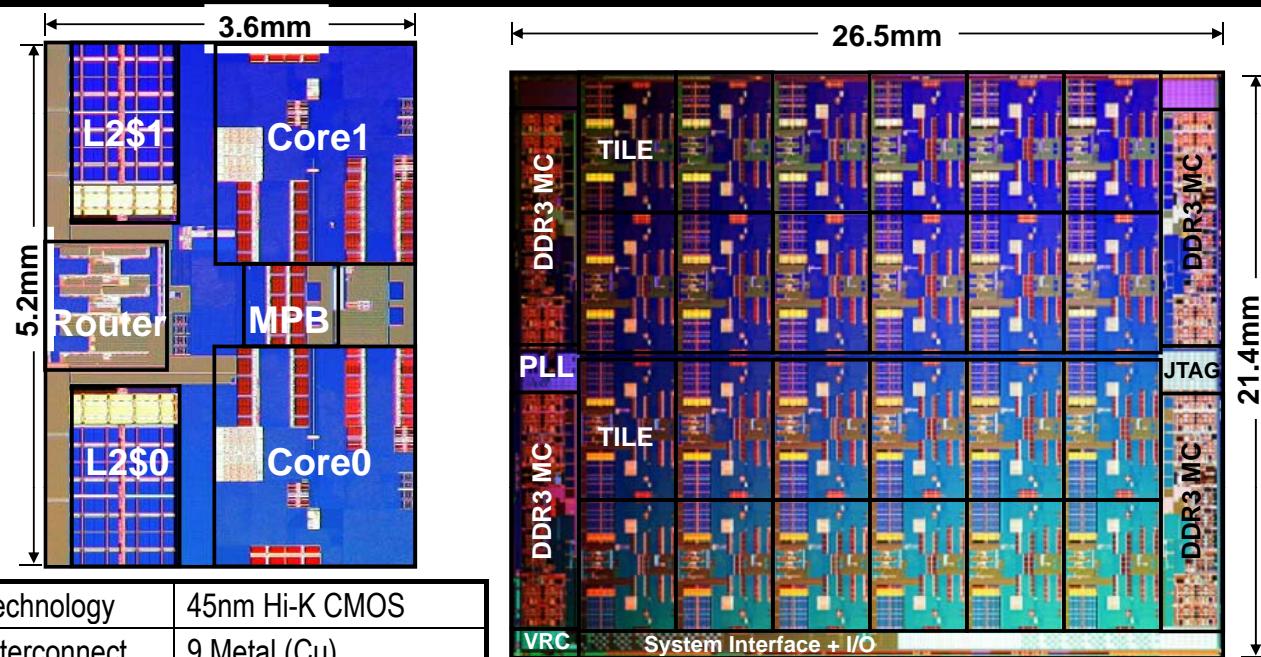


Name: # = 0 to 7	Meaning	Type of Voltage	Min.	Max.
VDD_NEST	Logic supply for nest & pervasive logic	Fixed, Static	1.0V	1.2V
VSB	Supply for pervasive	Fixed, Static	1.1V	1.3V
VMEM 0/1	Supply for differential IO	Fixed, Static	0.95V	1.15V
VIO_SMT	Supply for IO receiver and transmitter	Fixed, Static	1.0V	1.2V

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33

## Intel 48-core SoC Processor



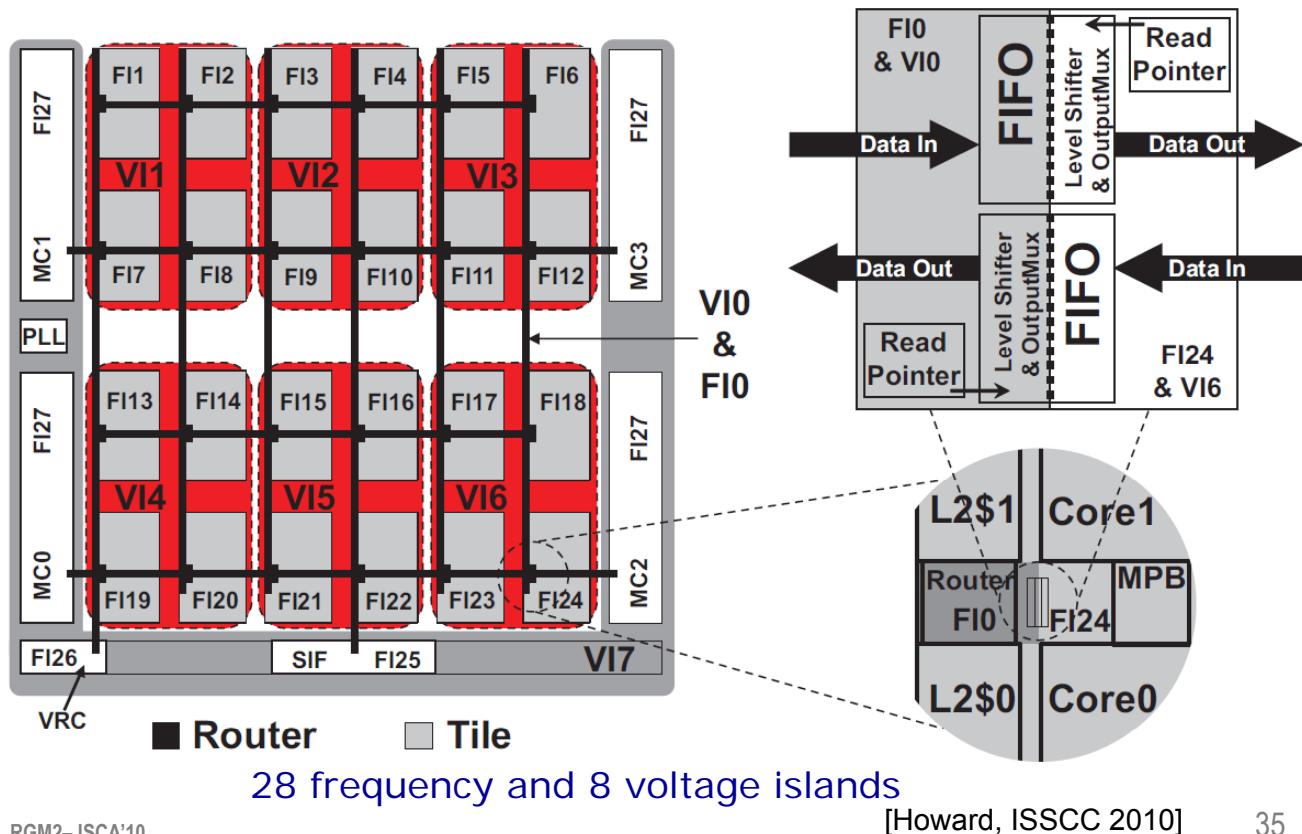
Technology	45nm Hi-K CMOS
Interconnect	9 Metal (Cu)
Transistors	Die: 1.3B, Tile: 48M
Tile Area	18.7mm <sup>2</sup>
Die Area	567.1mm <sup>2</sup>

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[Howard, ISSCC 2010]

34

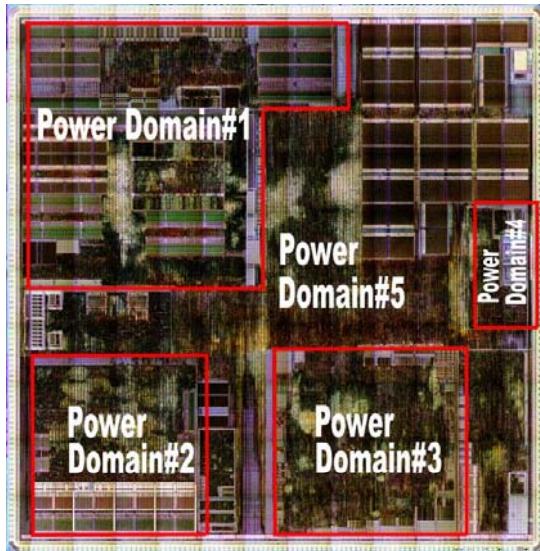
# Voltage and Frequency Islands



## Multi-Domain Processors Design Overview

- Voltage / frequency scaling basics
- Multi-domain server processors
- Cell phone processors
- Media processors
- Dual voltage supply at the cell level
- Future directions
- Summary

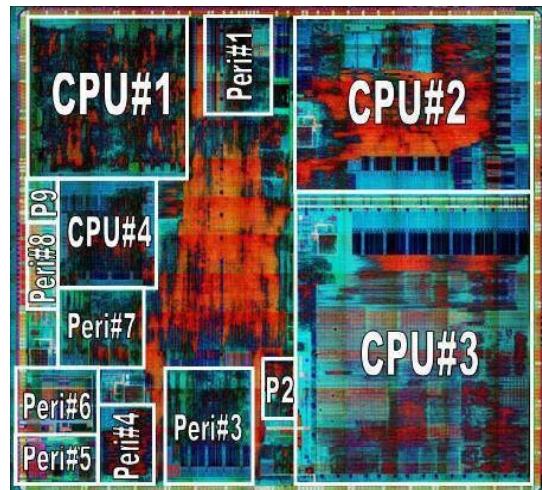
# TI Application Processors



- 90nm OMAP2
- 1 voltage domain
- 5 power domains

[Royannez, ISSCC 2005]

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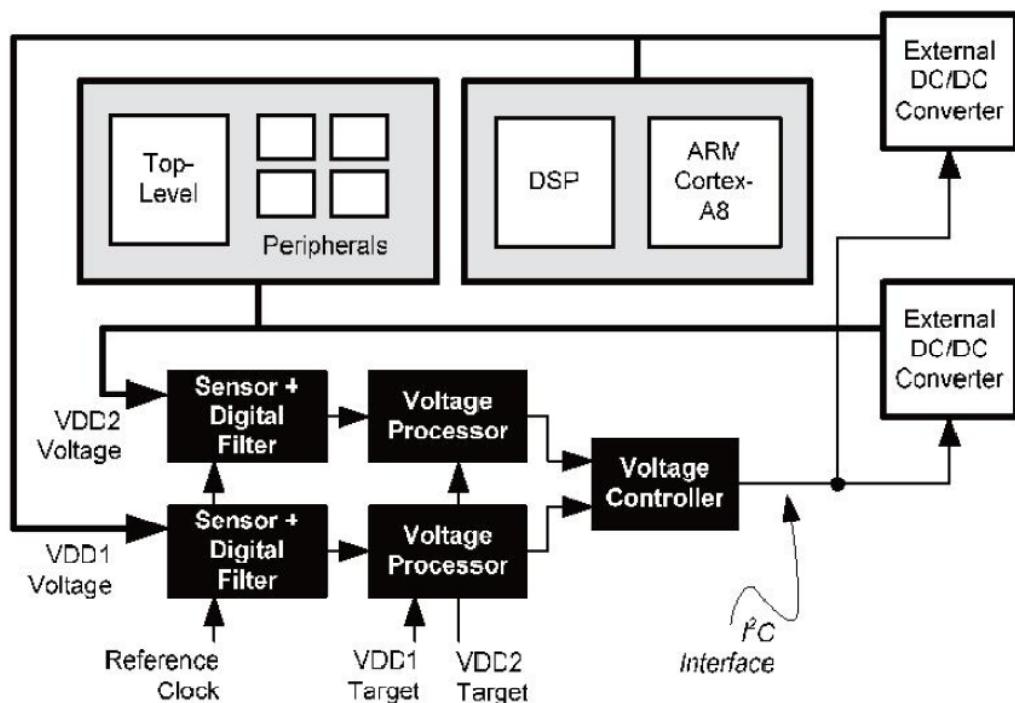


- 65nm OMAP3
- 2 voltage domains
- 11 major power domains

[Mair, VLSI Symp. 2007]

37

## Adaptive Voltage Scaling Control Loop

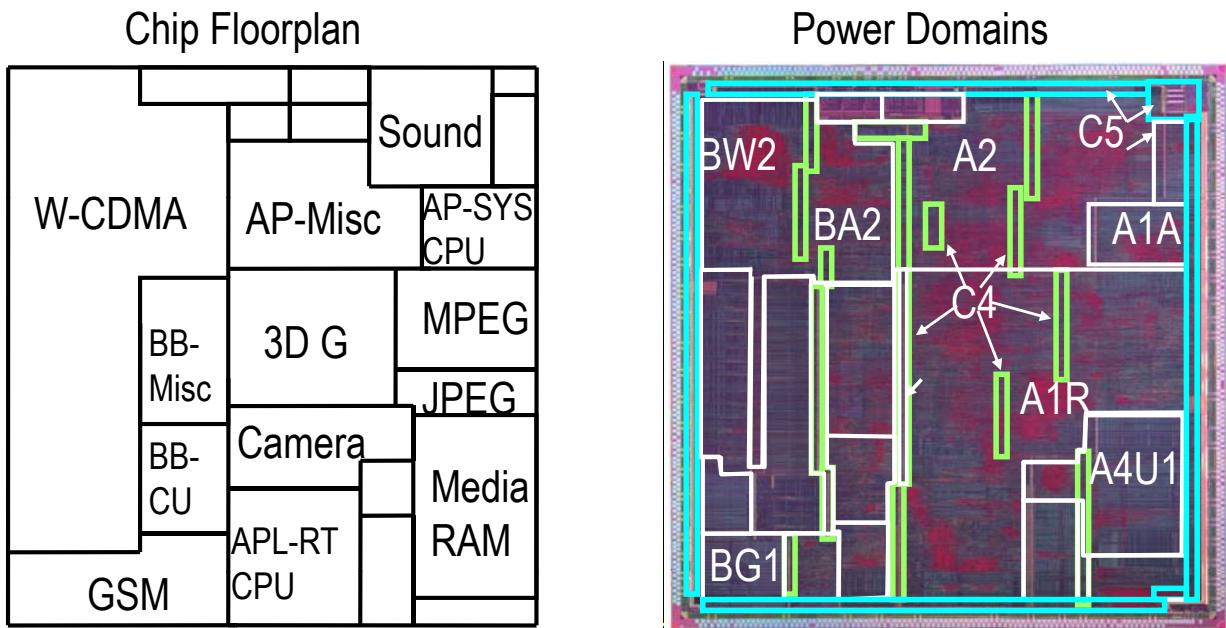


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[Mair, VLSI Symp. 2007]

38

# Renesas 90nm Cell Phone Processor



20 power domains for partial power-off,  
C4 (common) domain for repeaters

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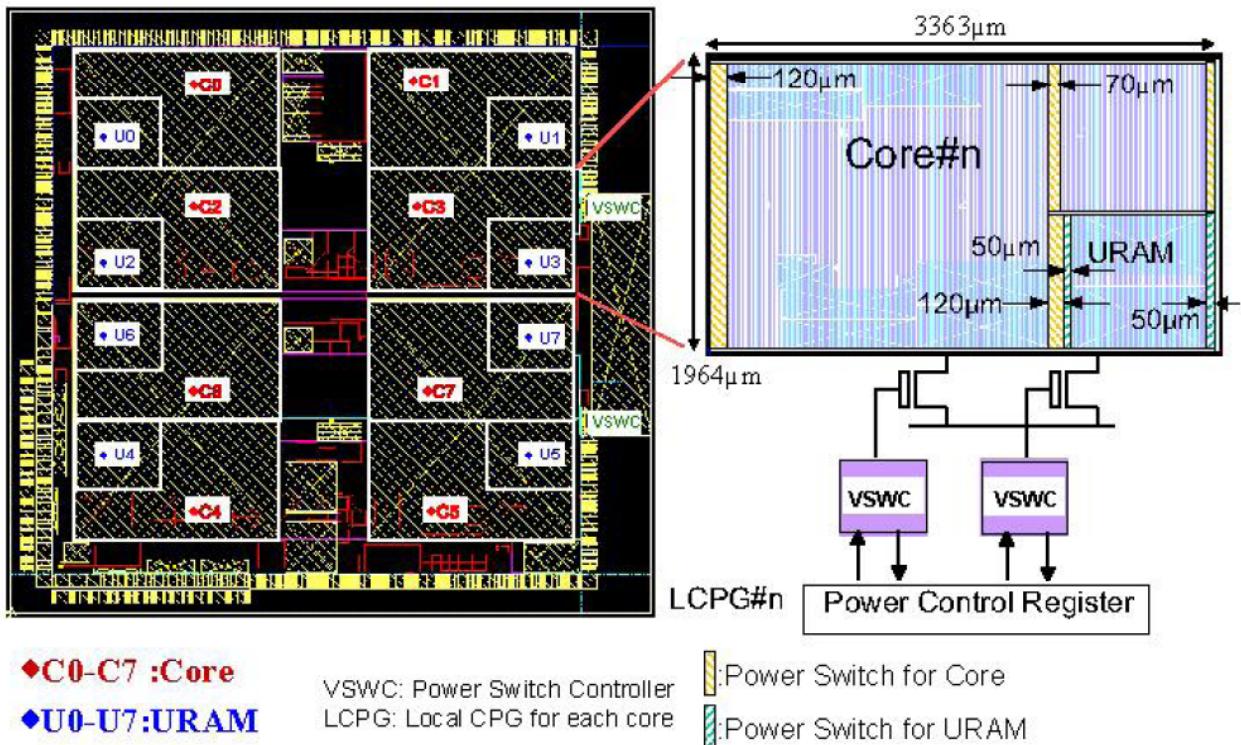
[Hattori, ISSCC 2006]

39

## Implementation Details

# of Power domains	20 domains
# of Islands for C4 (Repeaters, CK buffers, BKUP FFs)	19 islands
# of Repeaters in C4 domain	3100 cells
# of Clock buffers in C4 domain	1600 cells
# of Backup FFs in C4 domain	2300 cells
# of $\mu$ IOs (isolation cell)	20000 cells
Total area of power switch	4.2 mm <sup>2</sup>
Power switch area ratio in the chip	3.4 %
Power-off -> power-on time (one-by-one on)	<100 $\mu$ Sec

# Renesas 8-Core 90nm Processor

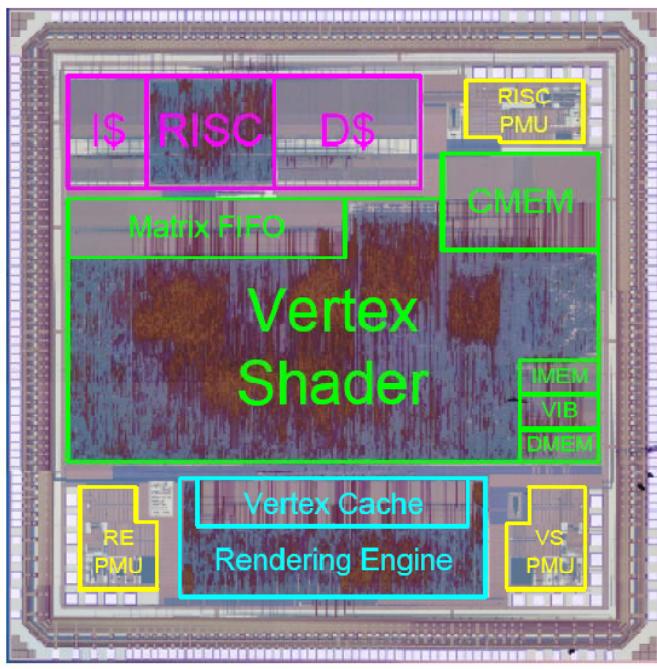


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[Ito, ISSCC 2008]

41

# Samsung 3D Graphics Processor



## Chip Characteristics

Technology	0.18um 1-P 6-M CMOS
Area	Core: 17.2mm <sup>2</sup> Die: 25mm <sup>2</sup>
Power supply	Core: 1.0V - 1.8V IO: 3.3V
Frequency	RISC: Max. 200MHz GP: Max. 200MHz RE: Max. 50MHz
Transistors	1.6M logic, 29KB SRAM
Processing speed	RISC: 200MIPS VS: 141Mvertices/s RE: 50Mpixels/s
Power consumption	52.4mW @ 60fps 153mW @ full speed

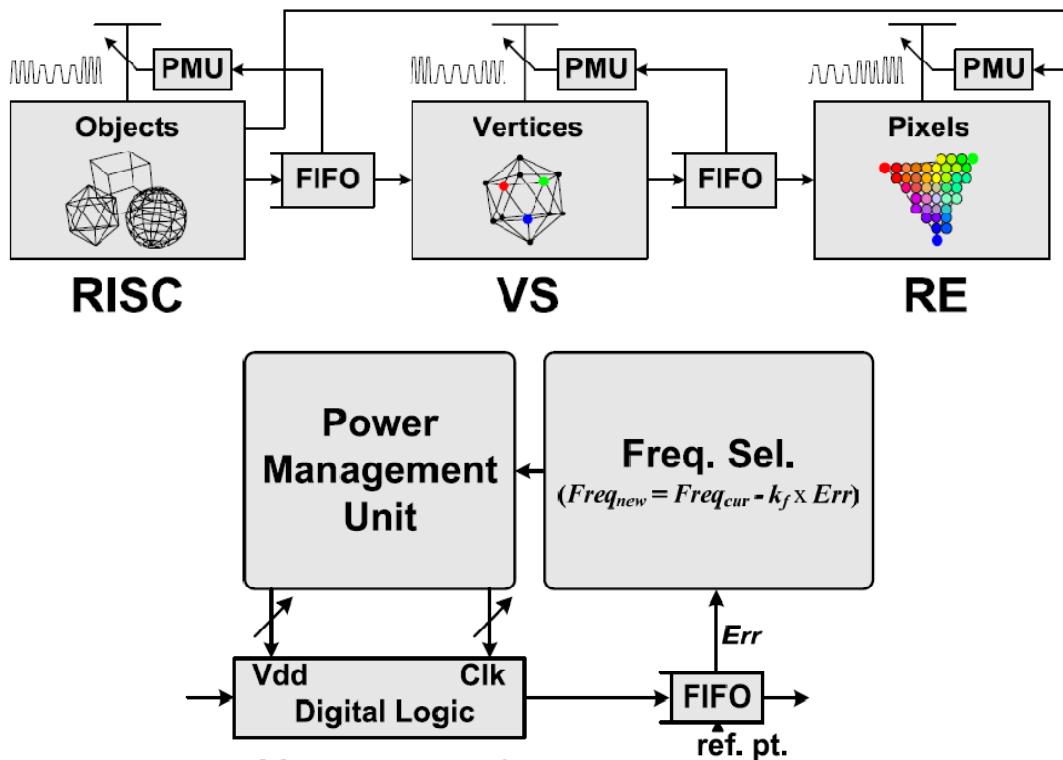
Three power domains with independent dynamic voltage-frequency scaling

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[Nam, ISSCC 2007]

42

# Multiple-Domain Power Management

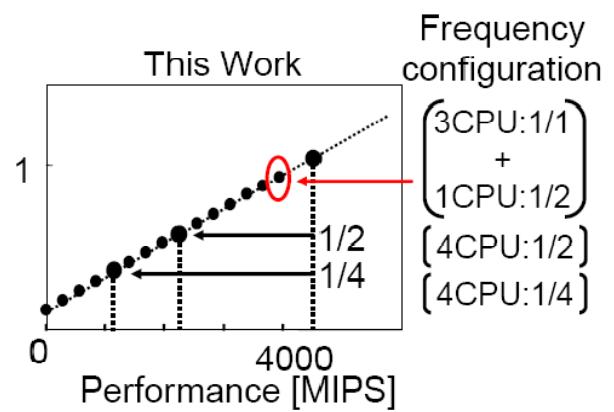
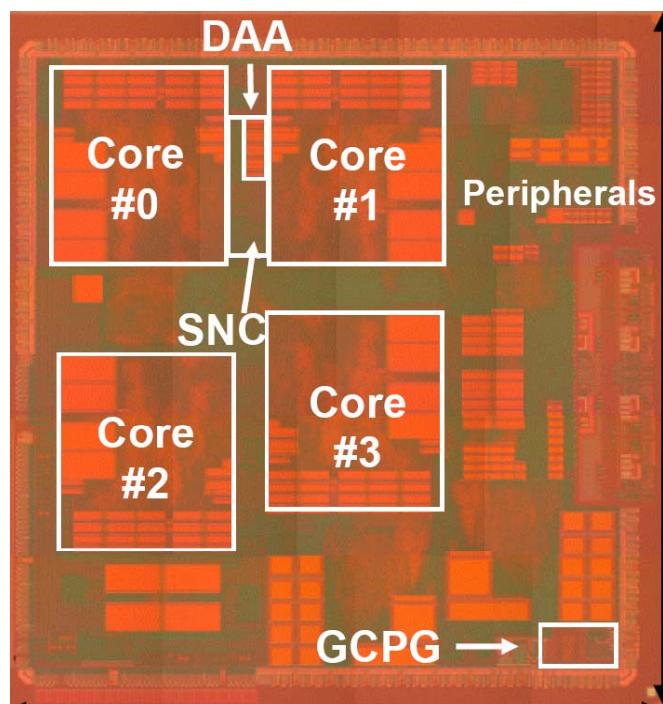


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[Nam, ISSCC 2007]

43

# Individually Managed Core Clock Frequency



Individual core-level frequency control enables multiple performance points

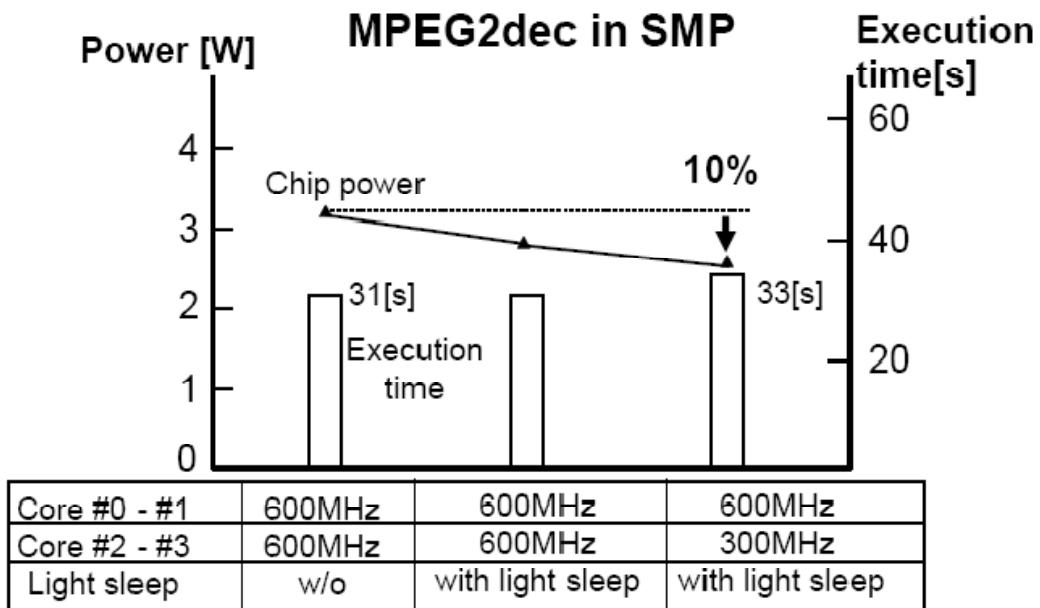
Renesas 90nm

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[Yoshida, ISSCC 2007]

44

## Power Reduction Benefits



Individual core clock distribution has modest power reduction benefits

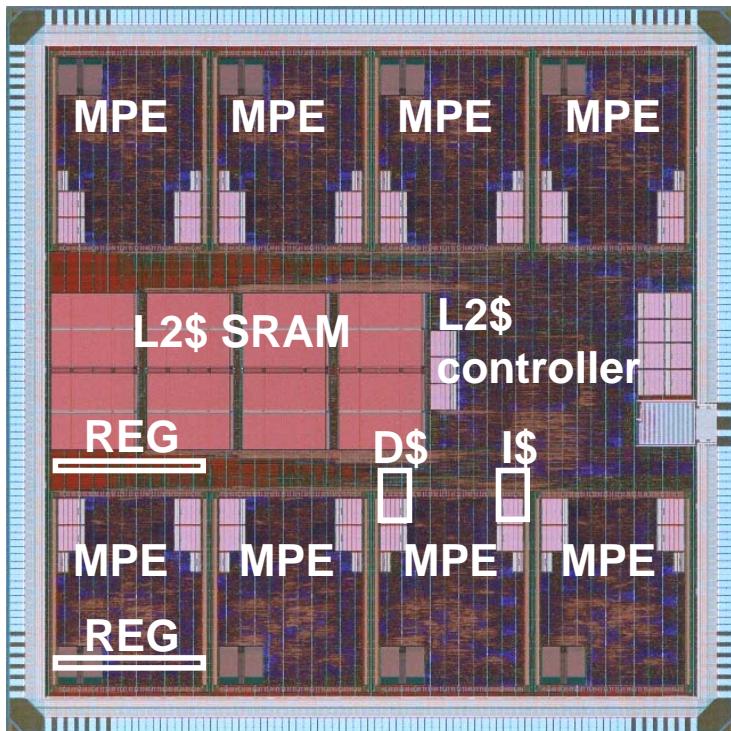
Much higher benefit achievable with separate voltage domains

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[Yoshida, ISSCC 2007]

45

## Toshiba's 8-Core Media Processor

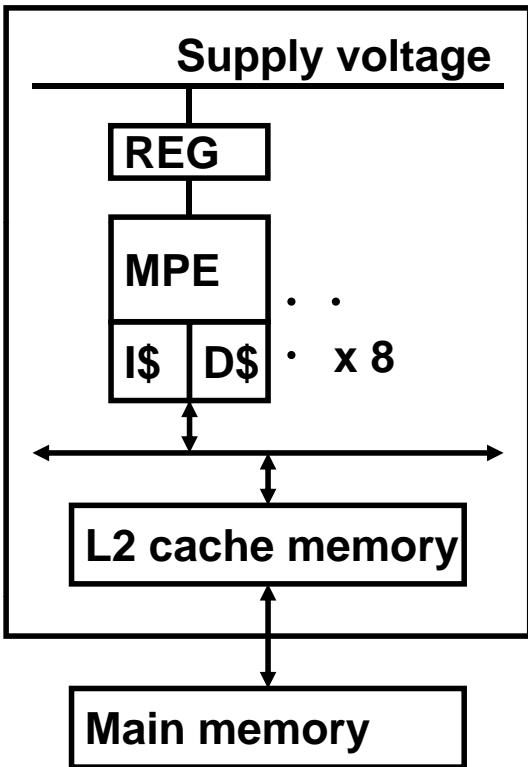


65nm CMOS  
8-layer-metal

Supply voltage  
2.5V (I/O)  
1.2V (core)  
1.2V / 0.95V / 0V  
(REG output)

Frequency  
333MHz  
(MPE / L2\$ logic)  
166MHz  
(L2\$ SRAM / bus I/F)

# Processor Architecture



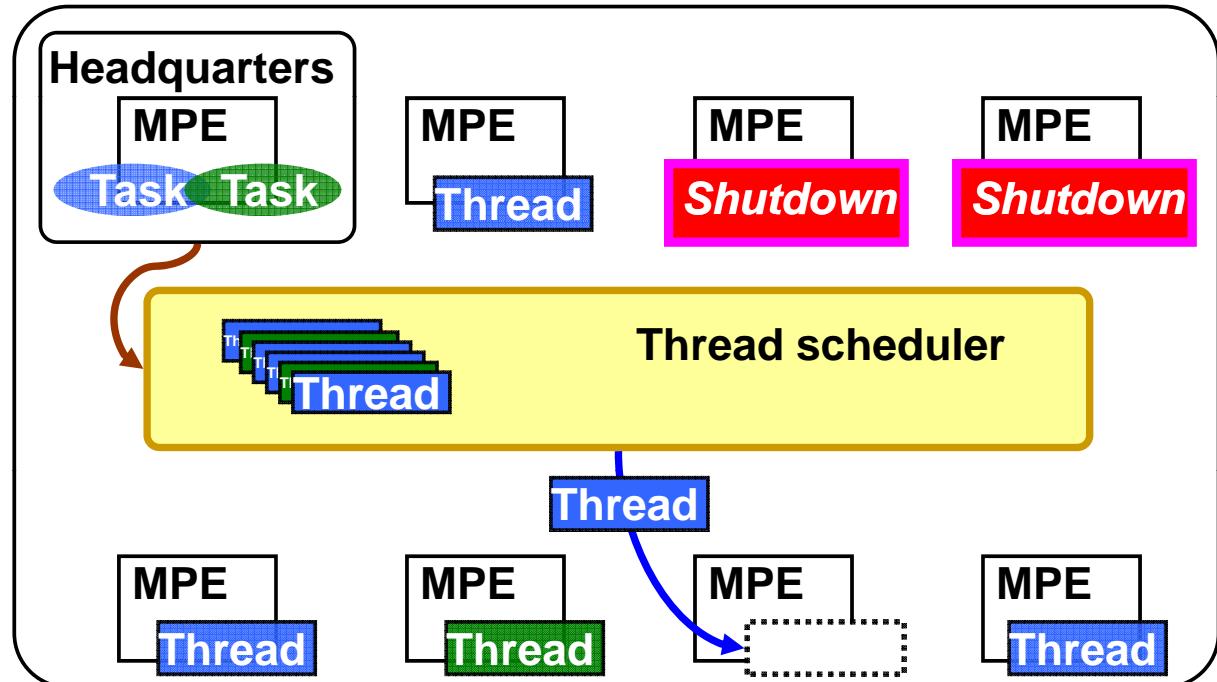
- MPE (Media Processing Engine)
  - 5-stage 32b RISC with 64b SIMD 2-way VLIW co-processor
- L1 cache (8KB I\$ + 8KB D\$)
- L2 cache
- Voltage regulator (REG)
  - Control of supplied voltage
  - 1.2V / 0.95V / 0V

RGM2- ISCA'10

[Ueda, A-SSCC 2008]

47

# Software Power Management



Shutdown MPEs at low work load

RGM2- ISCA'10

[Ueda, A-SSCC 2008]

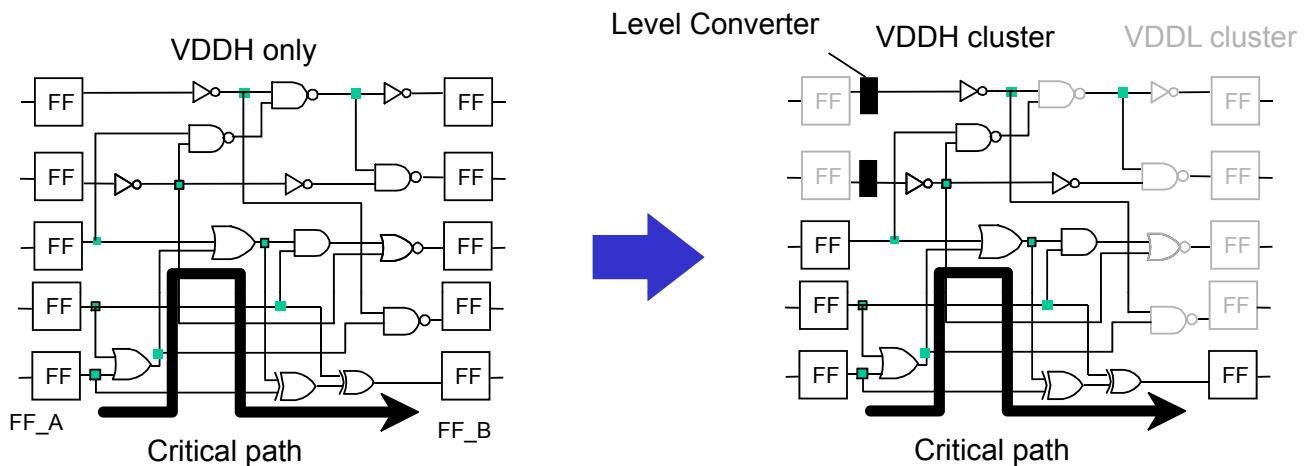
48

# Multi-Domain Processors Design Overview

- Voltage / frequency scaling basics
- Multi-domain server processors
- Cell phone processors
- Media processors
- Dual voltage supply at the cell level
- Future directions
- Summary

## Cell-Level Dual-VDD Approach

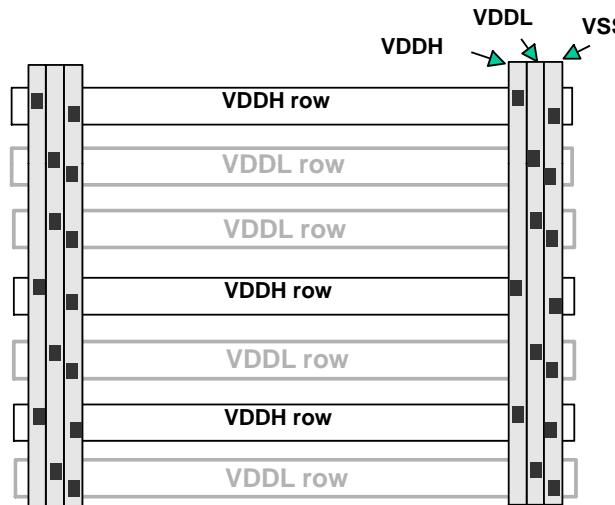
- Use reduced voltage  $VDDL$  in non-critical paths
- Apply original voltage  $VDDH$  to timing critical paths



Challenge: minimize number of level converters by clustering

## Cell-Level Dual-VDD (cont)

Row-by-Row layout architecture with Dual-V<sub>DD</sub>



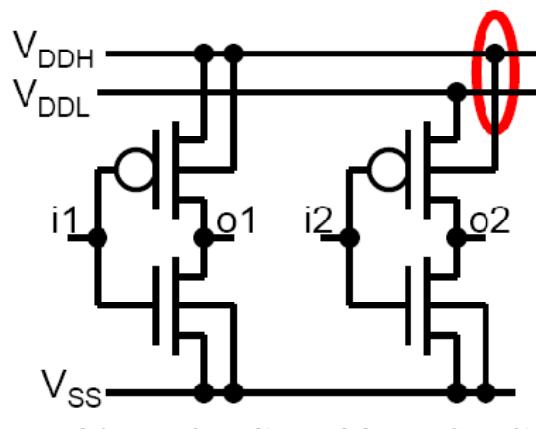
- P&R tool determines which rows should be *VDDL*
- Clock tree synthesis using *VDDL* clock buffers
- 25% power reduction on MPEG4 video codec core

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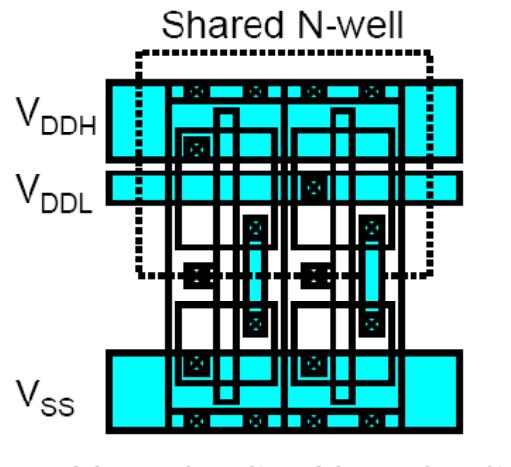
[Usami, DAC 1998]

51

## Shared Well Dual Supply



(a) circuit schematic



(b) layout

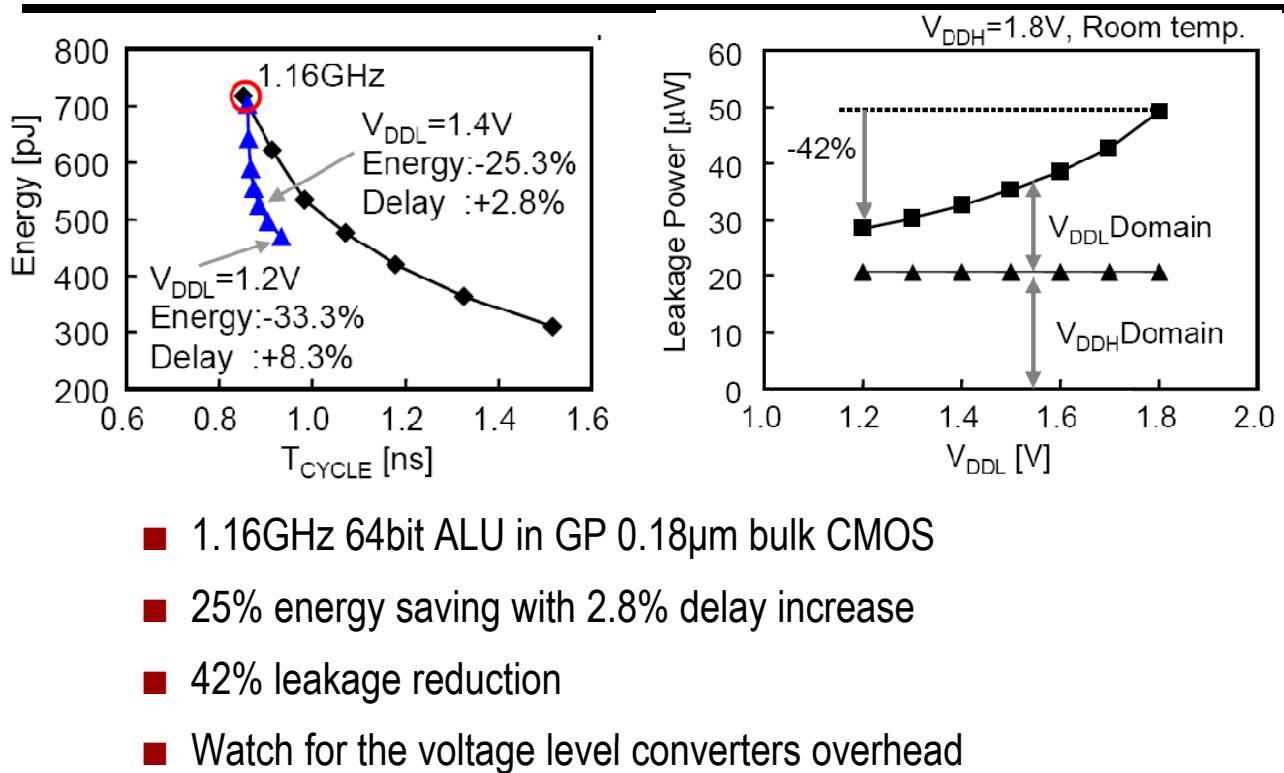
- Both circuits can be placed in the same N-well
- Cell layout becomes complex
- An intrinsic negative back-biasing of PMOS degrades speed

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[Shimazaki, ISSCC 2003]

52

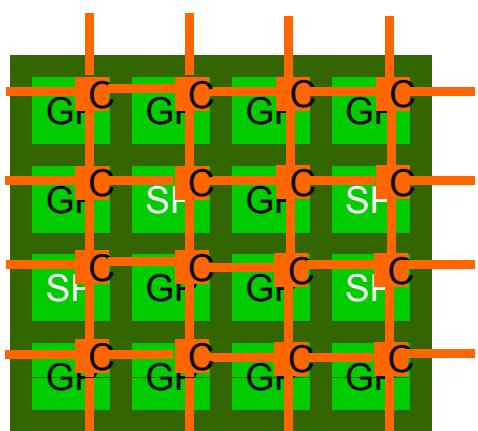
## Dual Supply ALU Test Chip Results



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[Shimazaki, ISSCC 2003] 53

## Future Directions for Multi-Core Platforms



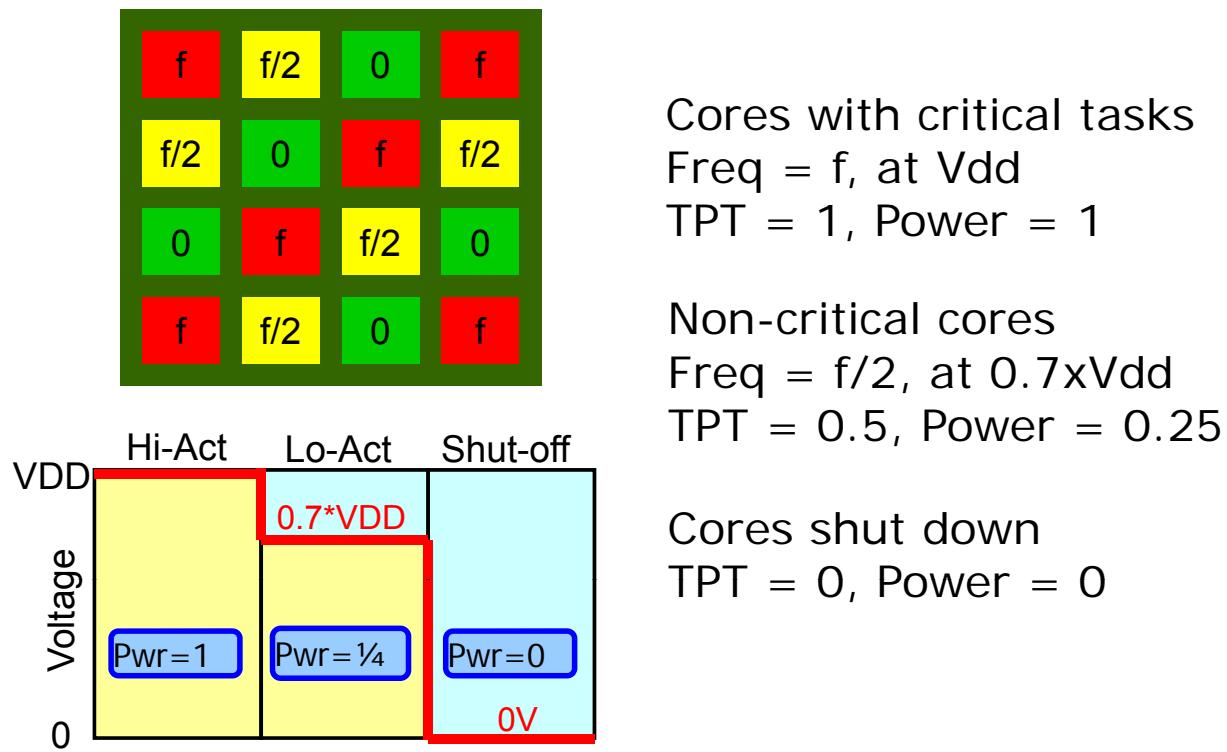
General Purpose Cores

Special Purpose HW

Interconnect fabric

Heterogeneous Multi-Core Platform—SoC

# Fine Grain Power Management



Cores with critical tasks

Freq = f, at Vdd

TPT = 1, Power = 1

Non-critical cores

Freq = f/2, at 0.7xVdd

TPT = 0.5, Power = 0.25

Cores shut down

TPT = 0, Power = 0

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[Adapted from S. Borkar, DAC 2007] 55

## Summary

- Multiple voltage and clock domains are widely used in modern processor design to manage power and process scaling issues
- Optimize voltage/frequency operating point for each block to minimize power consumption
- The need to shut-off unused logic is driving a finer granularity clock and power gating
- Core and cache recovery enables multiple product options where disabled cores and cache slices are clock and power gated
- Increased use of Globally Asynchronous Locally Synchronous (GALS) clocking for large SoC designs
- Managing all these voltage and frequency domains requires increased software complexity

# Outline

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- **Part I: Multi-Domain Processors Design Overview (2:00-2:45PM)**
  - ▶ Multi-domain server, cell phone, and media processors
  - ▶ Power management techniques
- **Part II: Router Design and Synchronization Issues (2:45-3:30PM)**
  - ▶ Asynchronous router design
  - ▶ Quality of Service and virtual channels in QNoC
- **Part III: Control and Power Management in Presence of Workload Variations (4:00-4:45PM)**
  - ▶ VFI partitioning and voltage assignment
  - ▶ Workload modeling and dynamic control of multi-VFI designs
- **Part IV: DVFS in Presence of Process Variations (4:45-5:30PM)**
  - ▶ Impact of process variations on DVFS controller performance
  - ▶ Technology-driven limits on DVFS controllability

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## ISCA-2010 Tutorial #2

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# The Asynchronous NOC

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